

Product Change Notification / ASER-060YDX227

Date:

11-Jan-2022

Product Category:

Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4999 Final Notice: Qualification of G700LA as a new mold compound for selected KSZ9031xxx device family available in 48L VQFN (7x7x0.9mm) and 64L VQFN (8x8x0.9mm) packages assembled at ASCL.

Affected CPNs:

ASER-06OYDX227_Affected_CPN_01112022.pdf ASER-06OYDX227_Affected_CPN_01112022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700LA as a new mold compound for selected KSZ9031xxx device family available in 48L VQFN (7x7x0.9mm) and 64L VQFN (8x8x0.9mm) packages assembled at ASCL.

Pre and Post Change Summary:

	Pre Change	Post Change			
Assembly Site	ASE Group Chung-Li	ASE Group Chung-Li			
	(ASCL)	(ASCL)			
Wire Material	Cu/CuPdAu	Cu/CuPdAu			
Die Attach Material	EN-4900GC	EN-4900GC			
Molding Compound Material	CEL-9240HF10AK	G700LA			
Lead-Frame Material	C194	C194			

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying G700LA as a new mold compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: February 17, 2022 (date code: 2208)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2022				February 2022					
Workweek	1	2	3	4	5	6	7	8	9	1 0
Qual Report Availability			х							
Final PCN Issue Date			х							
Estimated Implementation Date								х		

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: January 11, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ASER-06OYDX227 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. ASER-06OYDX227 - CCB 4999 Final Notice: Qualification of G700LA as a new mold compound for selected KSZ9031xxx device family available in 48L VQFN (7x7x0.9mm) and 64L VQFN (8x8x0.9mm) packages assembled at ASCL.

Affected Catalog Part Numbers (CPN)

KSZ9031RNXCC KSZ9031MNXCC KSZ9031RNXIC KSZ9031MNXIC KSZ9031RNXCC-TR KSZ9031RNXIC-TR KSZ9031MNXIC-TR